

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
25 March 2004 (25.03.2004)

PCT

(10) International Publication Number
WO 2004/024339 A1

(51) International Patent Classification⁷: B05B 5/08,
15/04, A61K 9/20

(21) International Application Number:
PCT/GB2003/003926

(22) International Filing Date:
11 September 2003 (11.09.2003)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
0221293.4 13 September 2002 (13.09.2002) GB

(71) Applicant (for all designated States except US): PHOQUS
PHARMACEUTICALS LIMITED [GB/GB]; 10 Kings
Hill Avenue, Kings Hill, West Malling, Kent ME19 4PQ
(GB).

(72) Inventor; and

(75) Inventor/Applicant (for US only): HALLETT, Martin,
David [GB/GB]; 62 Park Avenue, Northfleet, Gravesend,
Kent DA11 8DS (GB).

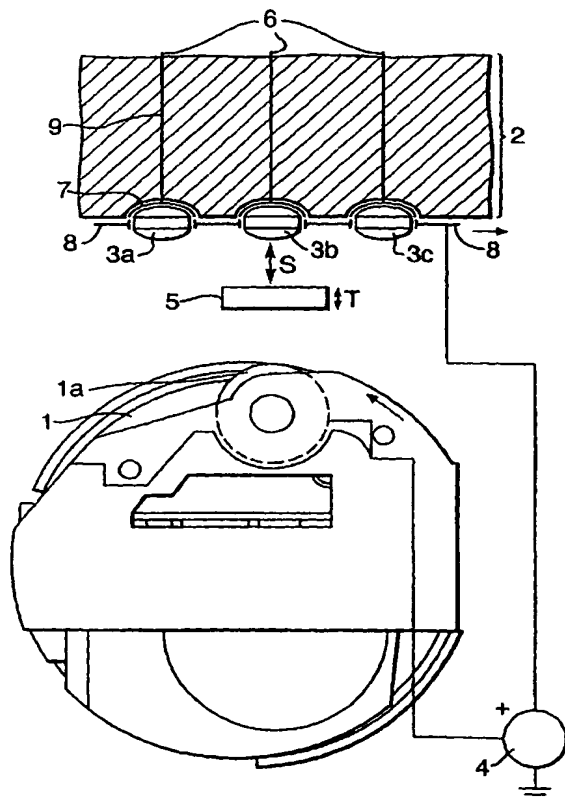
(74) Agents: BARDO, Julian, Eason et al.; Abel & Imray, 20
Red Lion Street, London WC1R 4PQ (GB).

(81) Designated States (national): AE, AG, AL, AM, AT, AU,
AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU,
CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE,
GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR,
KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK,
MN, MW, MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT,
RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR,
TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (regional): ARIPO patent (GH, GM,
KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW),
Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM),
European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE,

[Continued on next page]

(54) Title: METHOD AND APPARATUS FOR APPLYING POWDER IN A PATTERN TO A SUBSTRATE



(57) Abstract: A method and apparatus for providing a pattern on a solid dosage form, in which powder material is applied in a pattern to a substrate (3). A mask (5) having an aperture is provided between a source (1) of the powder material and the substrate (3) and the powder material is applied to the substrate through the mask (5). Relative movement of the substrate with respect to the source (1) of powder material is effected during the pattern application process.

WO 2004/024339 A1



ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO,
SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM,
GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

Published:

— *with international search report*